L Number	Hits	Search Text	DB	Time stamp
16	732590	(liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:12
19	55089	((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:14
20	30793	(((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:14
21	1898	((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:15
22	98	(((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4) near (phase or state)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:16
23	69	((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4) near (phase or state)) and epoxy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:16
24	46	((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4) near (phase or state)) and (solder or paste or cream)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:16
26	132	((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4 or increas$6 or decreas$4) near (pressure)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:17
27	110	((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4 or increas$6 or decreas$4) near (vol or volume or expan$7 or contract$7)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:20
28	43	((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4 or increas$6 or decreas$4) near (potential)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:18

29	1031	(((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4 or increas$6 or decreas$4 or high$4 or low$4) near (temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:19
30	548	((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4 or increas$6 or decreas$4 or high$4 or low$4) near (temperature)) and dimension	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:19
31	72	((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4) near (phase or state)) and (optic$4 adj (fiber or fibre) or (fiber or fibre) adj optic$4 or laser or lens or led or diode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:23
32	68	((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4 or increas$6 or decreas$4) near (vol or volume or expan$7 or contract$7)) and (cool$6 or quench$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:21
33	89	((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4 or increas$6 or decreas$4) near (vol or volume or expan$7 or contract$7)) and (expand$4 or expans$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:21
34	0	((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4 or increas$6 or decreas$4) near (vol or volume or expan$7 or contract$7)) and sump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:22
35	11	((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4 or increas$6 or decreas$4) near (vol or volume or expan$7 or contract$7)) and (tank or container or vat or bath or reservoir or pot or supply) near (liquid or fluid or adhesive or epoxy or rosin or resin or cream or paste or solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:23

36	71	((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4 or increas$6 or decreas$4) near (vol or volume or expan$7 or contract$7)) and (optic$4 adj (fiber or fibre) or (fiber or fibre) adj optic$4 or laser or lens or led or diode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:24
37	91	((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4) near (phase or state)) and heat$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:23
39	65	(((((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4) near (phase or state)) and heat$4) and (optic$4 adj (fiber or fibre) or (fiber or fibre) adj optic$4 or laser or lens or led or diode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:24
25	13	(((((liquid or fluid) and (flux or adhesive or epoxy or resin or paste or cream)) and (move or mov$4 or plac$6 or position$4 or mount$4) near (component or device or chip or die or wafer)) and adhesive) and (cure or curing or cured) near adhesive) and (chang$4 or shift$4 or increas$6 or decreas$4) near (surface adj tension)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/11 15:26